

**IN THE SPECIFICATION:**

Amend page 8, paragraph [0019] to read:

The spray nozzle [[106]] 108 is moved back and forth, substantially parallel to the surface of the substrate, on the swivel arm 110 by a motor 112 that is controlled by a control unit 114. The control unit 114 controls the position and speed at which the spray nozzle 108 moves.

Amend page 13, paragraph [0034] to read:

Figure 5 illustrates one method of priming a substrate prior to spray coating in relatively high humidity environments according to one embodiment of the invention. The substrate is first cleaned by dipping it into a cleaning solution 502. For instance, depending on the initial cleanliness and/or roughness of the substrate, the substrate may be dipped five (5) to fifteen (15) minutes in a cleaning solution such as Piranha (peroxide-sulfuric solution). In other implementations, the substrate may be cleaned in oxygen-plasma solution. The substrate is then rinsed with ultrapure water for five (5) to ten (10) minutes 504. The substrate is then thoroughly dried, by either spin or N2 purge for instance 506. Once dried, the substrate is primed by immersion into a priming liquid 508. For example, the substrate may be immersed in SurPass3000 liquid, with gentle agitation, for a period of thirty (30) to ninety (90) seconds. As a rule of thumb, substrates with deep features and high device densities require longer immersion time. The substrate is then immediately rinsed, in flowing ultrapure water for 30 seconds for instance 510. The substrate is then thoroughly dried, by either spin or N2 purge for instance 512.